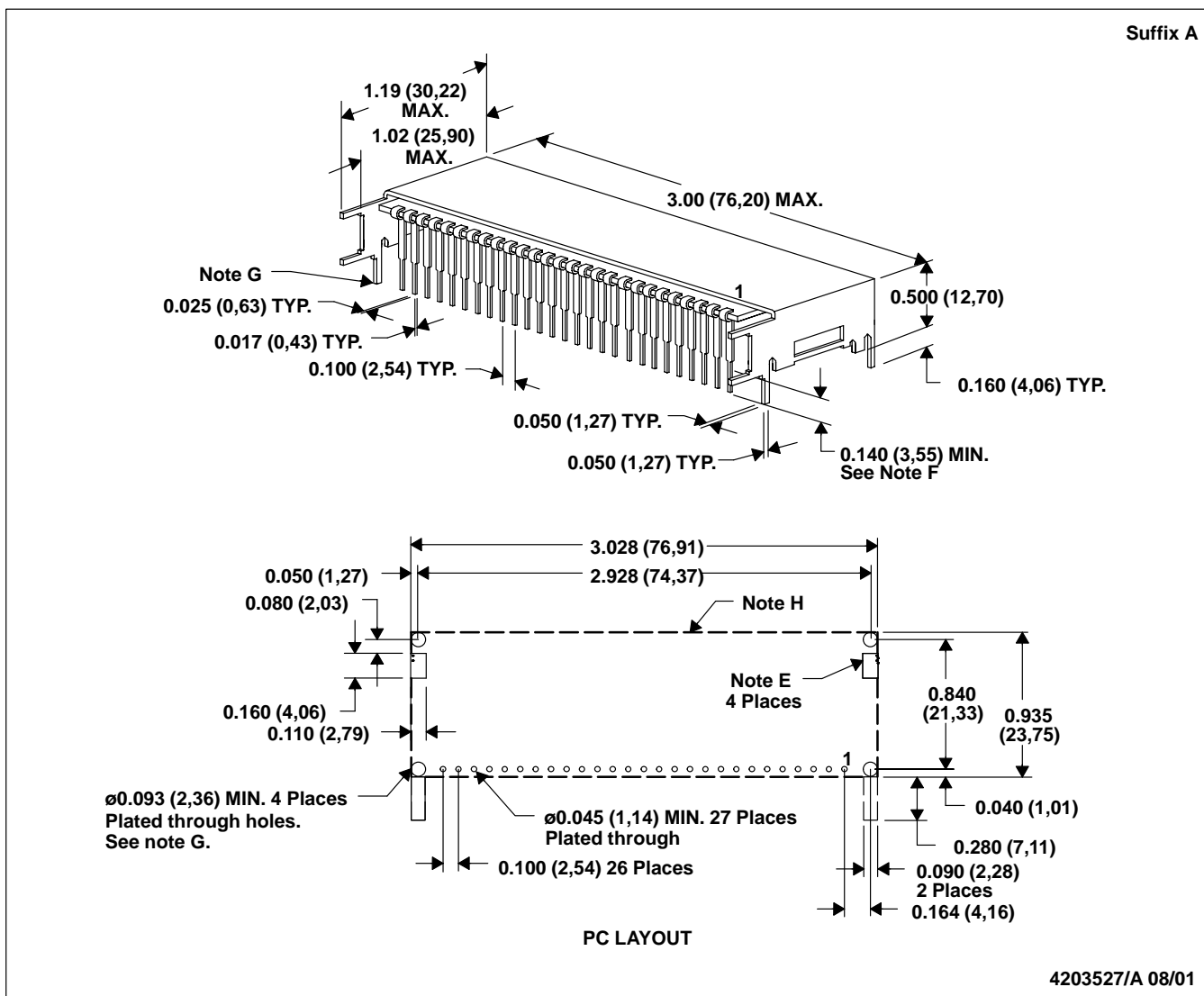


ENF (R-MSIP-T27)

METAL SINGLE-IN-LINE MODULE

Suffix A



4203527/A 08/01

- NOTES: A. All linear dimensions are in inches (mm).
 B. This drawing is subject to change without notice.
 C. 2 place decimals are ± 0.030 (± 0.76 mm).
 D. 3 place decimals are ± 0.010 (± 0.25 mm).
 E. Recommended mechanical keep out area.
 F. Electrical pin length mounted on printed circuit board, from seating plane to pin end.
 G. The case may be electrically connected to power ground plane.
 H. Case outline reference.

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